



Product Change Notification: MAAN-08UCSI636

Date:

15-Oct-2026

Product Category:

Power Management - System Supervisors/Voltage Detectors

Notification Subject:

CCB 8588 Initial Notice: Qualification of 8303A as a new die attach material, palladium coated copper with gold flash (CuPdAu) as a new wire material, and G700LTD as a new mold compound material for MIC706MY, MIC706PMY, MIC706RMY, MIC706SMY, MIC706TMY, MIC707MY, MIC708MY, MIC708RMY, MIC708SMY, MIC708TMY, MIC708SMY-TR, MIC708TMY-TR, MIC705MY, MIC705MY-TR, MIC706MY-TR, MIC706PMY-TR, MIC706RMY-TR, MIC706SMY-TR, MIC706TMY-TR, MIC707MY-TR, MIC708MY-TR, MIC708RMY-TR, MIC1232MY, MIC1232MY-TR, MIC1832MY and MIC1832MY-TR catalog part numbers (CPN) available in 8L SOIC (.150in) package at STAR assembly site.

Affected CPNs:

[MAAN-08UCSI636_Affected_CPN_10152026.pdf](#)

[MAAN-08UCSI636_Affected_CPN_10152026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 8303A as a new die attach material, palladium coated copper with gold flash (CuPdAu) as a new wire material, and G700LTD as a new mold compound material for MIC706MY, MIC706PMY, MIC706RMY, MIC706SMY, MIC706TMY, MIC707MY, MIC708MY, MIC708RMY, MIC708SMY, MIC708TMY, MIC708SMY-TR, MIC708TMY-TR, MIC705MY, MIC705MY-TR, MIC706MY-TR, MIC706PMY-TR, MIC706RMY-TR, MIC706SMY-TR, MIC706TMY-TR, MIC707MY-TR, MIC708MY-TR, MIC708RMY-TR, MIC1232MY, MIC1232MY-TR, MIC1832MY and MIC1832MY-TR catalog part numbers (CPN) available in 8L SOIC (.150in) package at STAR assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Stars Microelectronics (Thailand) Public Company Limited (STAR)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	2200D (PFAS)	8303A (PFAS Free)	Yes
Molding Compound Material	G600	G700LTD	Yes
Lead-Frame Material	A194	A194	No
Lead-Frame Paddle Size	130 x 95 mils	158 x 100 mils	Yes
Lead-Frame Design	See Pre and Post Change Summary Attachment for Comparison.		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 8303A as a new die attach material, palladium coated copper with gold flash (CuPdAu) as a new wire material, and G700LTD as a new mold compound material at STAR assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026	>	March 2027
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Work Week	40	41	42	43	44		09	10	11	12	13
Initial PCN Issue Date			x								
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 15, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_MAAN-08UCSI636 Pre and Post Change Summary.pdf
PCN_MAAN-08UCSI636_Qual Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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